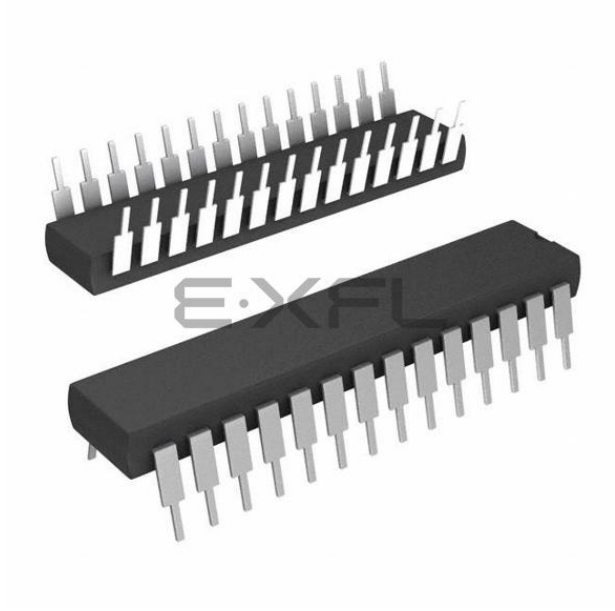
Microchip Technology - DSPIC33FJ128MC202-E/SP Datasheet



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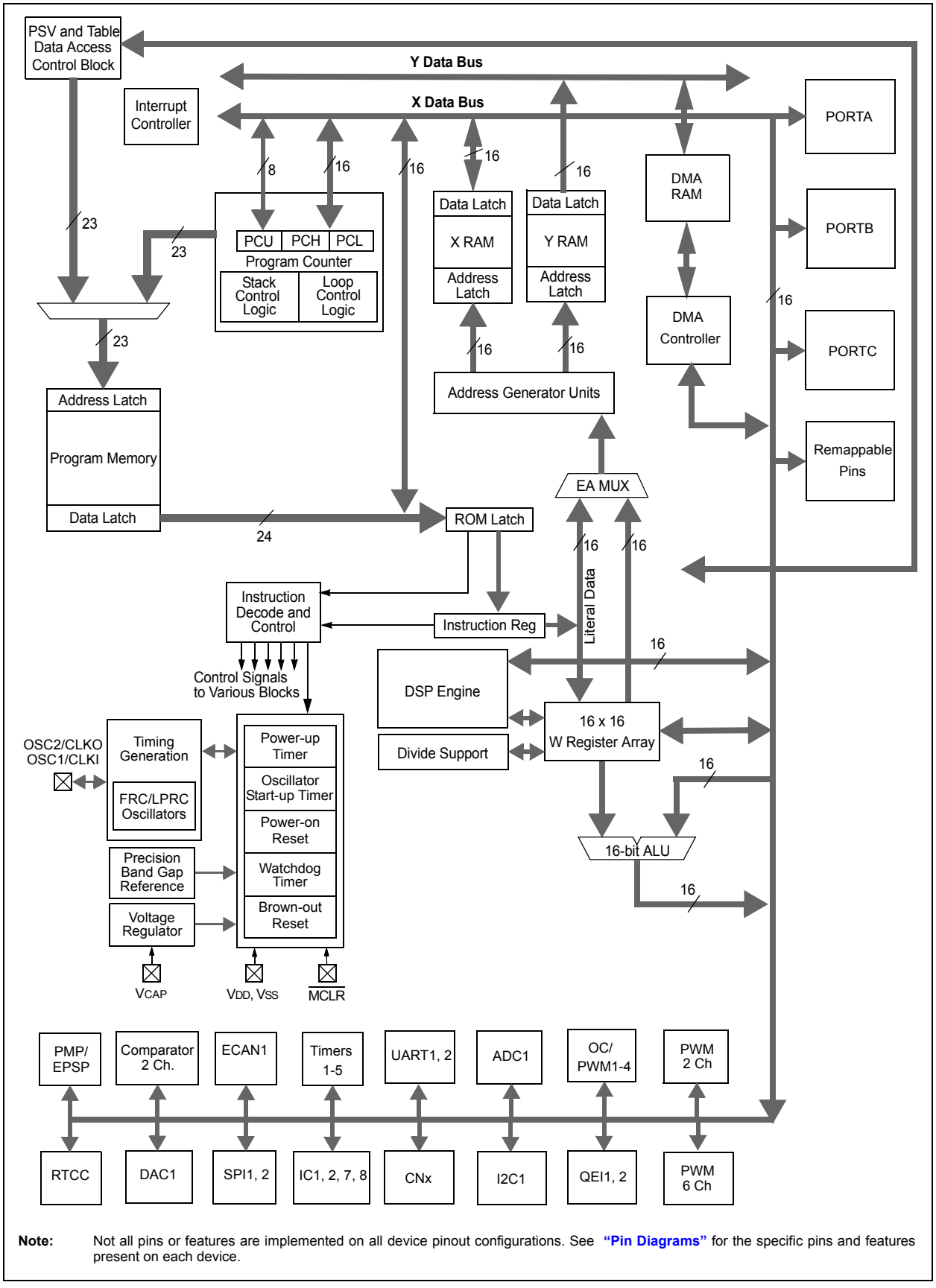
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	21
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128mc202-e-sp

FIGURE 1-1: dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 AND dsPIC33FJ128MCX02/X04 BLOCK DIAGRAM



Note: Not all pins or features are implemented on all device pinout configurations. See **"Pin Diagrams"** for the specific pins and features present on each device.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 family of 16-bit Digital Signal Controllers (DSC) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used) (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used (see **Section 2.6 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins used when external voltage reference for ADC module is implemented

Note: The AVDD and AVSS pins must be connected independent of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

REGISTER 3-2: CORCON: CORE CONTROL REGISTER

U-0	U-0	U-0	R/W-0	R/W-0	R-0	R-0	R-0
—	—	—	US	EDT(1)	DL<2:0>		
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R/W-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3(2)	PSV	RND	IF
bit 7							bit 0

Legend:	C = Clear only bit		
R = Readable bit	W = Writable bit	-n = Value at POR	'1' = Bit is set
'0' = Bit is cleared	'x' = Bit is unknown	U = Unimplemented bit, read as '0'	

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **US:** DSP Multiply Unsigned/Signed Control bit
1 = DSP engine multiplies are unsigned
0 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit(1)
1 = Terminate executing DO loop at end of current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits
111 = 7 DO loops active
•
•
•
001 = 1 DO loop active
000 = 0 DO loops active

bit 7 **SATA:** ACCA Saturation Enable bit
1 = Accumulator A saturation enabled
0 = Accumulator A saturation disabled

bit 6 **SATB:** ACCB Saturation Enable bit
1 = Accumulator B saturation enabled
0 = Accumulator B saturation disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit
1 = Data space write saturation enabled
0 = Data space write saturation disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit
1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(2)
1 = CPU interrupt priority level is greater than 7
0 = CPU interrupt priority level is 7 or less

bit 2 **PSV:** Program Space Visibility in Data Space Enable bit
1 = Program space visible in data space
0 = Program space not visible in data space

Note 1: This bit is always read as '0'.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU interrupt priority level.

3.8.1 MULTIPLIER

The 17-bit x 17-bit multiplier is capable of signed or unsigned operation and can multiplex its output using a scaler to support either 1.31 fractional (Q31) or 32-bit integer results. Unsigned operands are zero-extended into the 17th bit of the multiplier input value. Signed operands are sign-extended into the 17th bit of the multiplier input value. The output of the 17-bit x 17-bit multiplier/scaler is a 33-bit value that is sign-extended to 40 bits. Integer data is inherently represented as a signed two's complement value, where the Most Significant bit (MSb) is defined as a sign bit. The range of an N-bit two's complement integer is -2^{N-1} to $2^{N-1} – 1$.

- For a 16-bit integer, the data range is -32768 (0x8000) to 32767 (0x7FFF) including 0
- For a 32-bit integer, the data range is -2,147,483,648 (0x8000 0000) to 2,147,483,647 (0x7FFF FFFF)

When the multiplier is configured for fractional multiplication, the data is represented as a two's complement fraction, where the MSb is defined as a sign bit and the radix point is implied to lie just after the sign bit (QX format). The range of an N-bit two's complement fraction with this implied radix point is -1.0 to $(1 – 2^{1-N})$. For a 16-bit fraction, the Q15 data range is -1.0 (0x8000) to 0.999969482 (0x7FFF) including 0 and has a precision of 3.01518×10^{-5}. In Fractional mode, the 16 x 16 multiply operation generates a 1.31 product that has a precision of 4.65661×10^{-10}.

The same multiplier is used to support the MCU multiply instructions, which include integer 16-bit signed, unsigned and mixed sign multiply operations.

The `MUL` instruction can be directed to use byte or word-sized operands. Byte operands direct a 16-bit result, and word operands direct a 32-bit result to the specified registers in the W array.

3.8.2 DATA ACCUMULATORS AND ADDER/SUBTRACTER

The data accumulator consists of a 40-bit adder/subtracter with automatic sign extension logic. It can select one of two accumulators (A or B) as its pre-accumulation source and post-accumulation destination. For the `ADD` and `LAC` instructions, the data to be accumulated or loaded can be optionally scaled using the barrel shifter prior to accumulation.

3.8.2.1 Adder/Subtracter, Overflow and Saturation

The adder/subtracter is a 40-bit adder with an optional zero input into one side, and either true or complement data into the other input.

- In the case of addition, the Carry/$\overline{\text{Borrow}}$ input is active-high and the other input is true data (not complemented)
- In the case of subtraction, the Carry/$\overline{\text{Borrow}}$ input is active-low and the other input is complemented

The adder/subtracter generates Overflow Status bits, SA/SB and OA/OB, which are latched and reflected in the STATUS register:

- Overflow from bit 39: this is a catastrophic overflow in which the sign of the accumulator is destroyed
- Overflow into guard bits 32 through 39: this is a recoverable overflow. This bit is set whenever all the guard bits are not identical to each other.

The adder has an additional saturation block that controls accumulator data saturation, if selected. It uses the result of the adder, the Overflow Status bits described previously and the SAT<A:B> (CORCON<7:6>) and ACCSAT (CORCON<4>) mode control bits to determine when and to what value to saturate.

Six STATUS register bits support saturation and overflow:

- OA: ACCA overflowed into guard bits
- OB: ACCB overflowed into guard bits
- SA: ACCA saturated (bit 31 overflow and saturation)
  or
  ACCA overflowed into guard bits and saturated (bit 39 overflow and saturation)
- SB: ACCB saturated (bit 31 overflow and saturation)
  or
  ACCB overflowed into guard bits and saturated (bit 39 overflow and saturation)
- OAB: Logical OR of OA and OB
- SAB: Logical OR of SA and SB

The OA and OB bits are modified each time data passes through the adder/subtracter. When set, they indicate that the most recent operation has overflowed into the accumulator guard bits (bits 32 through 39). The OA and OB bits can also optionally generate an arithmetic warning trap when set and the corresponding Overflow Trap Flag Enable bits (OVATE, OVBTE) in the INTCON1 register are set (refer to **Section 7.0 "Interrupt Controller"**). This allows the user application to take immediate action, for example, to correct system gain.

The SA and SB bits are modified each time data passes through the adder/subtracter, but can only be cleared by the user application. When set, they indicate that the accumulator has overflowed its maximum range (bit 31 for 32-bit saturation or bit 39 for 40-bit saturation) and is saturated (if saturation is enabled). When saturation is not enabled, SA and SB default to bit 39 overflow and thus indicate that a catastrophic overflow has occurred. If the COVTE bit in the INTCON1 register is set, the SA and SB bits generate an arithmetic warning trap when saturation is disabled.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 4. "Program Memory"** (DS70203) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 architecture features separate program and data memory spaces and buses. This architecture also allows the direct access to program memory from the data space during code execution.

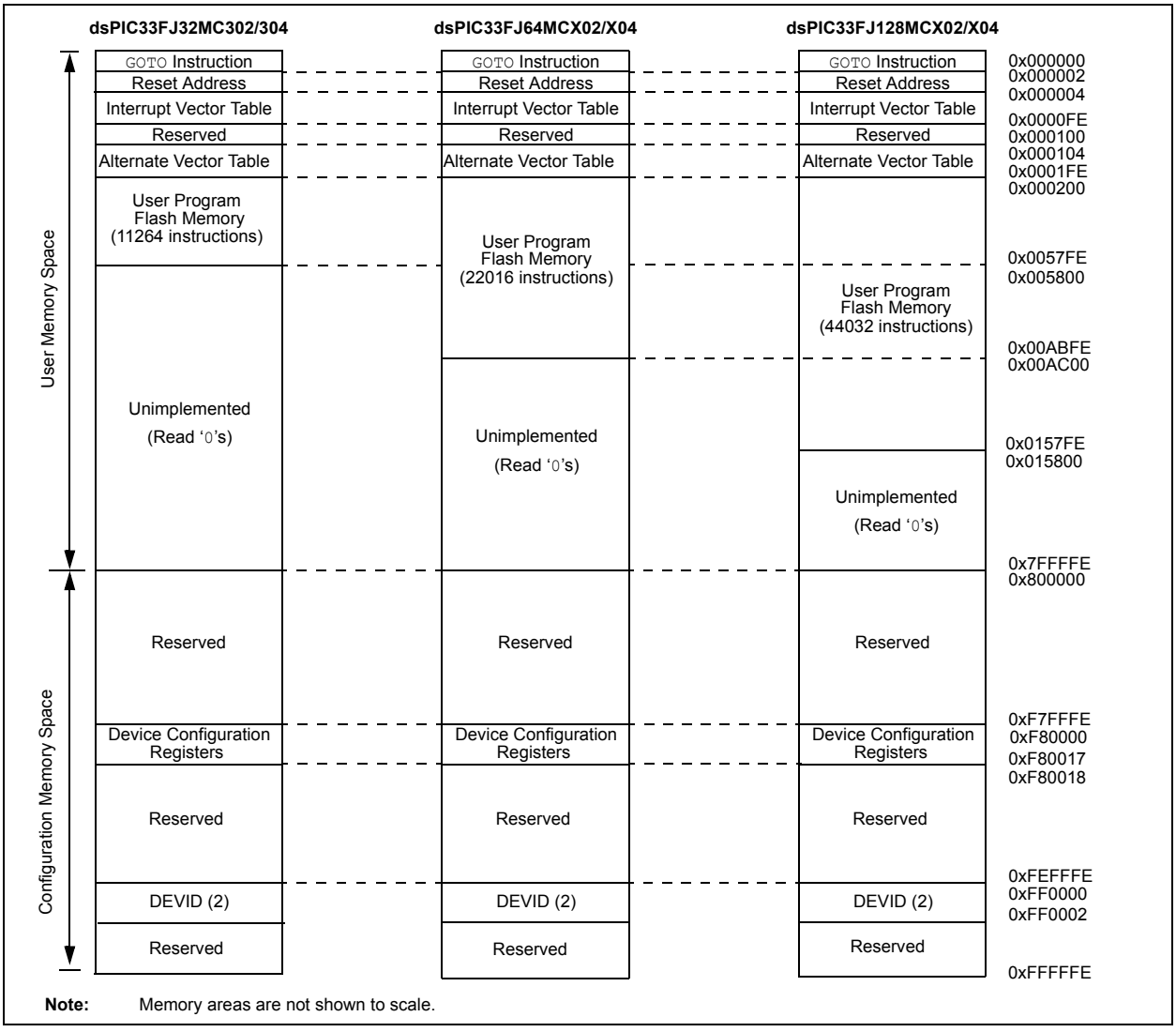
4.1 Program Address Space

The program address memory space of the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit Program Counter (PC) during program execution, or from table operation or data space remapping as described in **Section 4.8 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

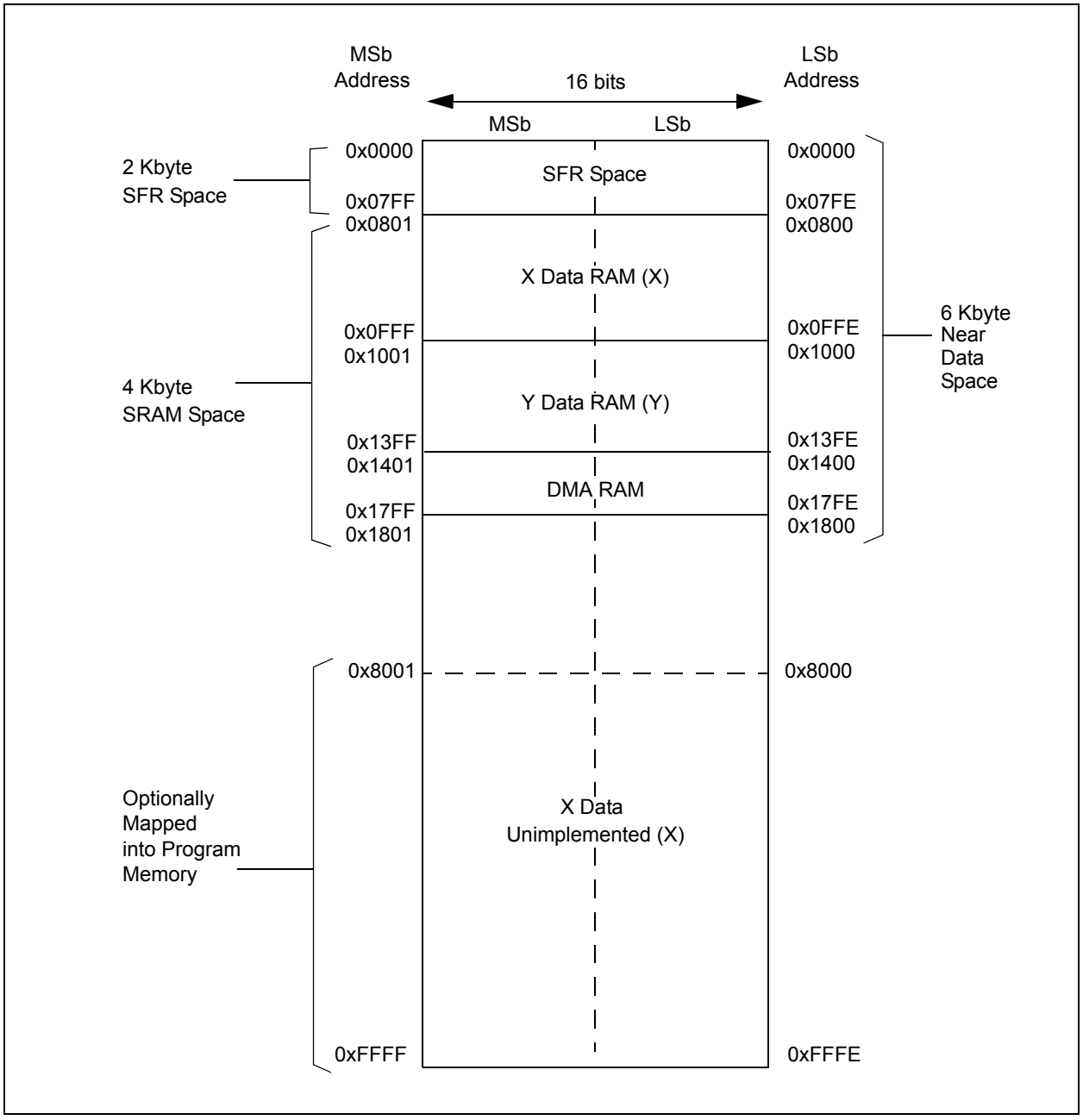
The memory map for the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 devices is shown in Figure 4-1.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 AND dsPIC33FJ128MCX02/X04 DEVICES



Note: Memory areas are not shown to scale.

FIGURE 4-3: DATA MEMORY MAP FOR dsPIC33FJ32MC302/304 DEVICES WITH 4 KB RAM



4.6.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

It is important to realize that the address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

Note:	The modulo corrected effective address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the effective address. When an address offset (such as [W7 + W2]) is used, Modulo Address correction is performed, but the contents of the register remain unchanged.

4.7 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data reordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Therefore, the only operand requiring reversal is the modifier.

4.7.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled in any of these situations:

- The BWM bits (W register selection) in the MODCON register are any value other than '15' (the stack cannot be accessed using Bit-Reversed Addressing)
- The BREN bit is set in the XBREV register
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last 'N' bits of the data buffer start address must be zeros.

The XB<14:0> bits is the Bit-Reversed Address modifier, or pivot point, which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note:	All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It does not function for any other addressing mode or for byte-sized data, and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB), and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note:	The Modulo Addressing and Bit-Reversed Addressing should not be enabled together. If an application attempts to do so, Bit-Reversed Addressing assumes priority when active for the X WAGU and X WAGU, Modulo Addressing is disabled. However, Modulo Addressing continues to function in the X RAGU.

If Bit-Reversed Addressing has already been enabled by setting the BREN bit (XBREV<15>), a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the bit-reversed pointer.

REGISTER 11-11: RPINR15: PERIPHERAL PIN SELECT INPUT REGISTER 15

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	INDX1R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as '0'

bit 4-0 **INDX1R<4:0>:** Assign QEI1 INDEX (INDX1) to the corresponding RPn pin

11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 11-12: RPINR16: PERIPHERAL PIN SELECT INPUT REGISTERS 16

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	QEB2R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	QEA2R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **QEB2R<4:0>:** Assign B (QEB2) to the corresponding pin

11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **QEA2R<4:0>:** Assign A (QEA2) to the corresponding pin

11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 11-17: RPINR21: PERIPHERAL PIN SELECT INPUT REGISTER 21

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SS1R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as '0'

bit 4-0 **SS1R<4:0>:** Assign SPI1 Slave Select Input ($\overline{SS1}$) to the corresponding RPn pin

11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 21-3: CiVEC: ECAN™ INTERRUPT CODE REGISTER

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	FILHIT<4:0>				
bit 15							bit 8

U-0	R-1	R-0	R-0	R-0	R-0	R-0	R-0
—	ICODE<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **FILHIT<4:0>:** Filter Hit Number bits

10000-11111 = Reserved
01111 = Filter 15
•
•
•
00001 = Filter 1
00000 = Filter 0

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **ICODE<6:0>:** Interrupt Flag Code bits

1000101-1111111 = Reserved
1000100 = FIFO almost full interrupt
1000011 = Receiver overflow interrupt
1000010 = Wake-up interrupt
1000001 = Error interrupt
1000000 = No interrupt
•
•
•
0010000-0111111 = Reserved
0001111 = RB15 buffer Interrupt
•
•
•
0001001 = RB9 buffer interrupt
0001000 = RB8 buffer interrupt
0000111 = TRB7 buffer interrupt
0000110 = TRB6 buffer interrupt
0000101 = TRB5 buffer interrupt
0000100 = TRB4 buffer interrupt
0000011 = TRB3 buffer interrupt
0000010 = TRB2 buffer interrupt
0000001 = TRB1 buffer interrupt
0000000 = TRB0 Buffer interrupt

22.6 ADC Control Registers

REGISTER 22-1: AD1CON1: ADC1 CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0 HC, HS	R/C-0 HC, HS
SSRC<2:0>			—	SIMSAM	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	HC = Cleared by hardware	HS = Set by hardware	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** ADC Operating Mode bit
1 = ADC module is operating
0 = ADC is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **ADDMABM:** DMA Buffer Build Mode bit
1 = DMA buffers are written in the order of conversion. The module provides an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer
0 = DMA buffers are written in Scatter/Gather mode. The module provides a scatter/gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer

bit 11 **Unimplemented:** Read as '0'

bit 10 **AD12B:** 10-bit or 12-bit Operation Mode bit
1 = 12-bit, 1-channel ADC operation
0 = 10-bit, 4-channel ADC operation

bit 9-8 **FORM<1:0>:** Data Output Format bits
For 10-bit operation:
11 = Signed fractional (DOUT = sddd dddd dd00 0000, where s =.NOT.d<9>)
10 = Fractional (DOUT = dddd dddd dd00 0000)
01 = Signed integer (DOUT = ssss sssd dddd dddd, where s = .NOT.d<9>)
00 = Integer (DOUT = 0000 00dd dddd dddd)
For 12-bit operation:
11 = Signed fractional (DOUT = sddd dddd dddd 0000, where s = .NOT.d<11>)
10 = Fractional (DOUT = dddd dddd dddd 0000)
01 = Signed Integer (DOUT = ssss sddd dddd dddd, where s = .NOT.d<11>)
00 = Integer (DOUT = 0000 dddd dddd dddd)

bit 7-5 **SSRC<2:0>:** Sample Clock Source Select bits
111 = Internal counter ends sampling and starts conversion (auto-convert)
110 = Reserved
101 = Motor Control PWM2 interval ends sampling and starts conversion
100 = GP timer (Timer5 for ADC1) compare ends sampling and starts conversion
011 = Motor Control PWM1 interval ends sampling and starts conversion
010 = GP timer (Timer3 for ADC1) compare ends sampling and starts conversion
001 = Active transition on INT0 pin ends sampling and starts conversion
000 = Clearing sample bit ends sampling and starts conversion

bit 4 **Unimplemented:** Read as '0'

25.2 RTCC Resources

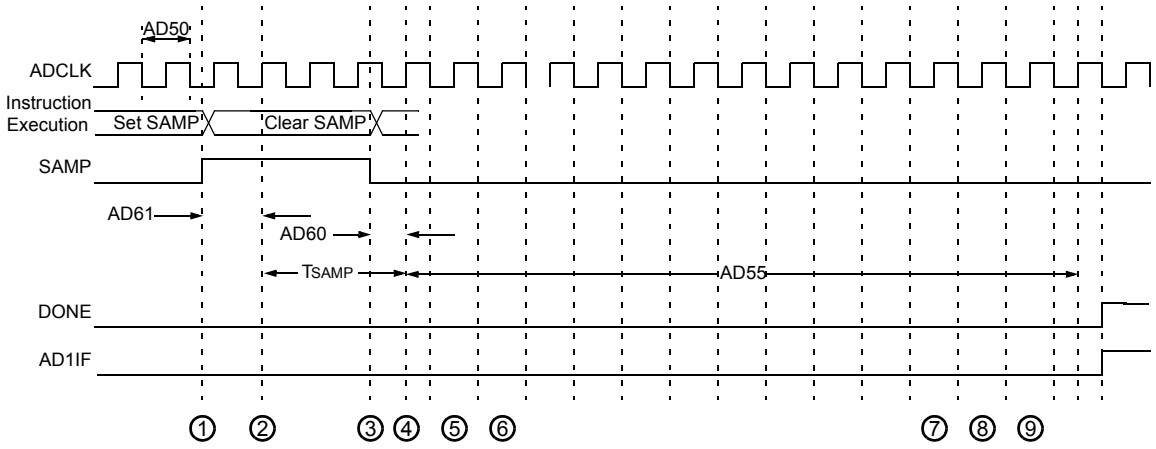
Many useful resources related to RTCC are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532315

25.2.1 KEY RESOURCES

- **Section 37. "Real-Time Clock and Calendar (RTCC)"** (DS70301)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

FIGURE 31-27: ADC CONVERSION (12-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets AD1CON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 28. "10/12-bit ADC without DMA" (DS70210)** in the *"dsPIC33F/PIC24H Family Reference Manual"*.

(3) – Software clears AD1CON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

(5) – Convert bit 11.

(6) – Convert bit 10.

(7) – Convert bit 1.

(8) – Convert bit 0.

(9) – One TAD for end of conversion.

TABLE 31-49: COMPARATOR TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
300	TRESP	Response Time(1,2)	—	150	400	ns	—
301	TMC2OV	Comparator Mode Change to Output Valid(1)	—	—	10	μs	—

Note 1: Parameters are characterized but not tested.

2: Response time measured with one comparator input at (VDD - 1.5)/2, while the other input transitions from VSS to VDD.

TABLE 31-50: COMPARATOR MODULE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
D300	VIOFF	Input Offset Voltage(1)	—	±10	—	mV	—
D301	VICM	Input Common Mode Voltage(1)	0	—	AVDD-1.5V	V	—
D302	CMRR	Common Mode Rejection Ratio(1)	-54	—	—	dB	—

Note 1: Parameters are characterized but not tested.

32.2 AC Characteristics and Timing Parameters

The information contained in this section defines dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 AC characteristics and timing parameters for high temperature devices. However, all AC timing specifications in this section are the same as those in **Section 31.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter OS53 in **Section 31.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 32-8: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+150°C for High Temperature Operating voltage VDD range as described in Table 32-1.

FIGURE 32-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

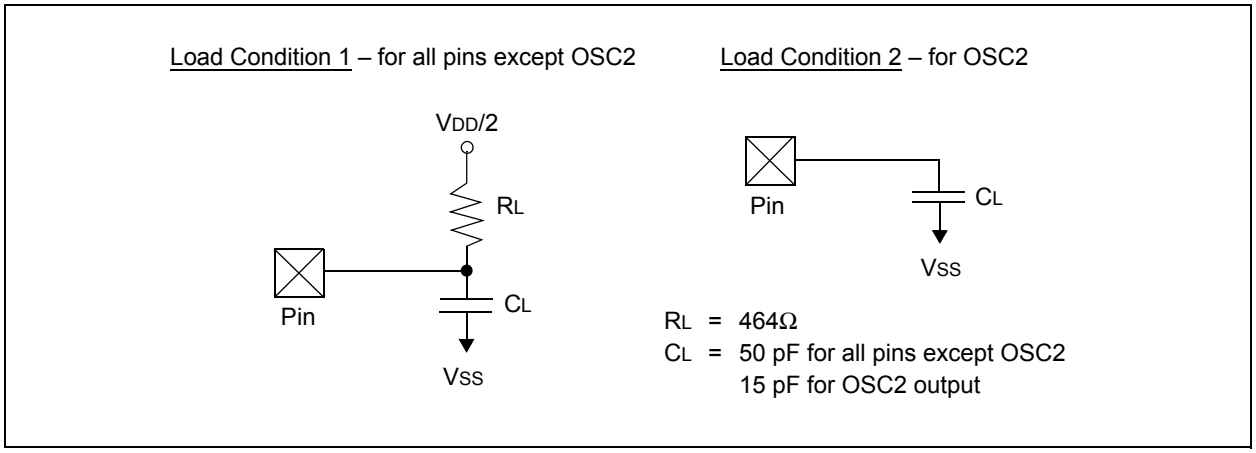


TABLE 32-9: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HOS53	DCLK	CLKO Stability (Jitter)(1)	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized, but are not tested in manufacturing.

FIGURE 32-5: VOL – 2x DRIVER PINS

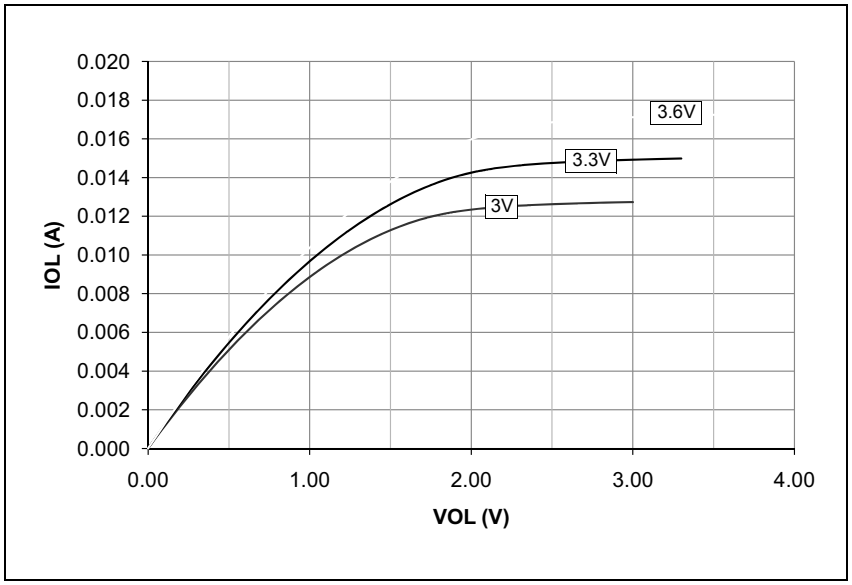


FIGURE 32-6: VOL – 4x DRIVER PINS

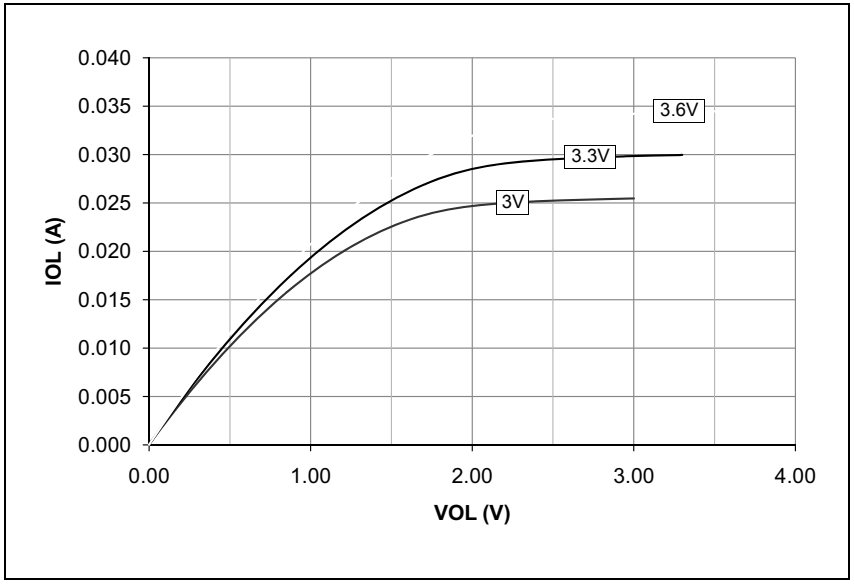


FIGURE 32-7: VOL – 8x DRIVER PINS

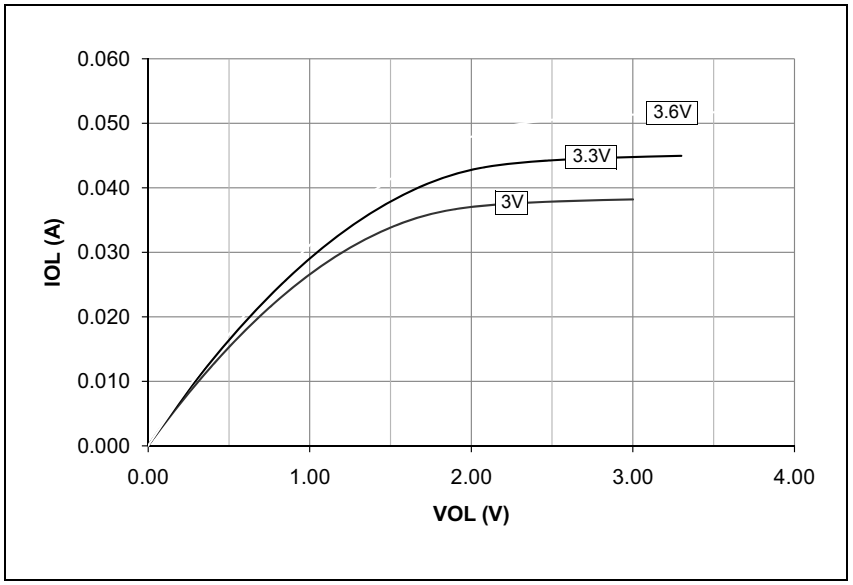
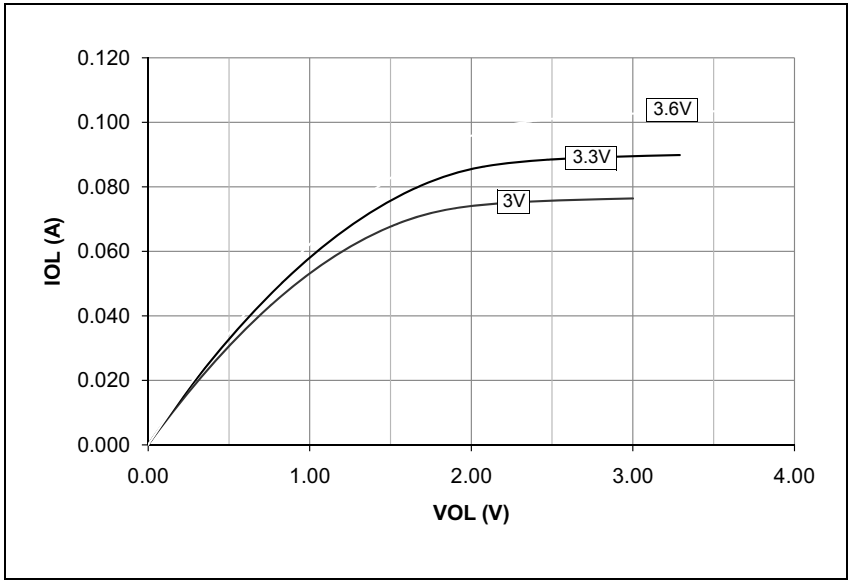
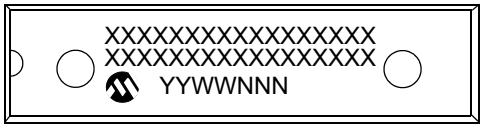


FIGURE 32-8: VOL – 16x DRIVER PINS

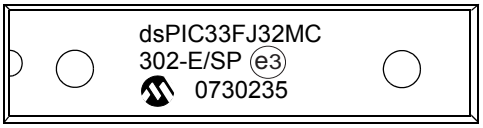


33.0 PACKAGING INFORMATION

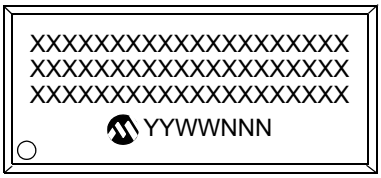
28-Lead SPDIP



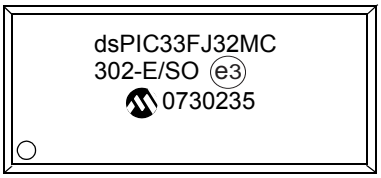
Example



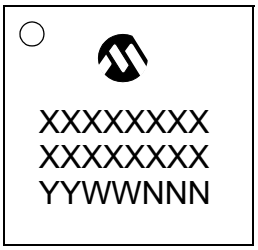
28-Lead SOIC (.300”)



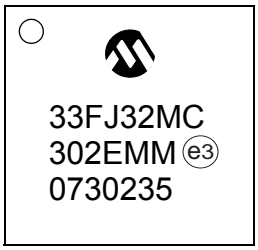
Example



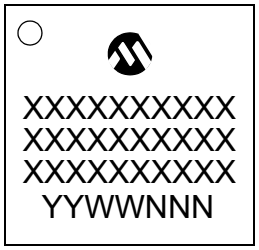
28-Lead QFN-S



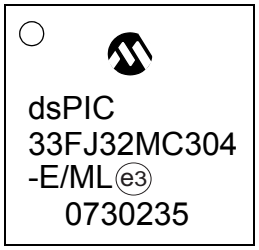
Example



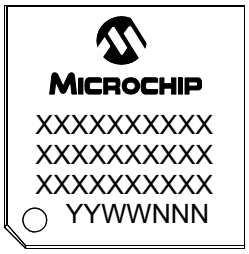
44-Lead QFN



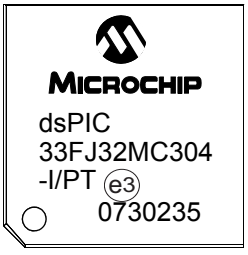
Example



44-Lead TQFP



Example

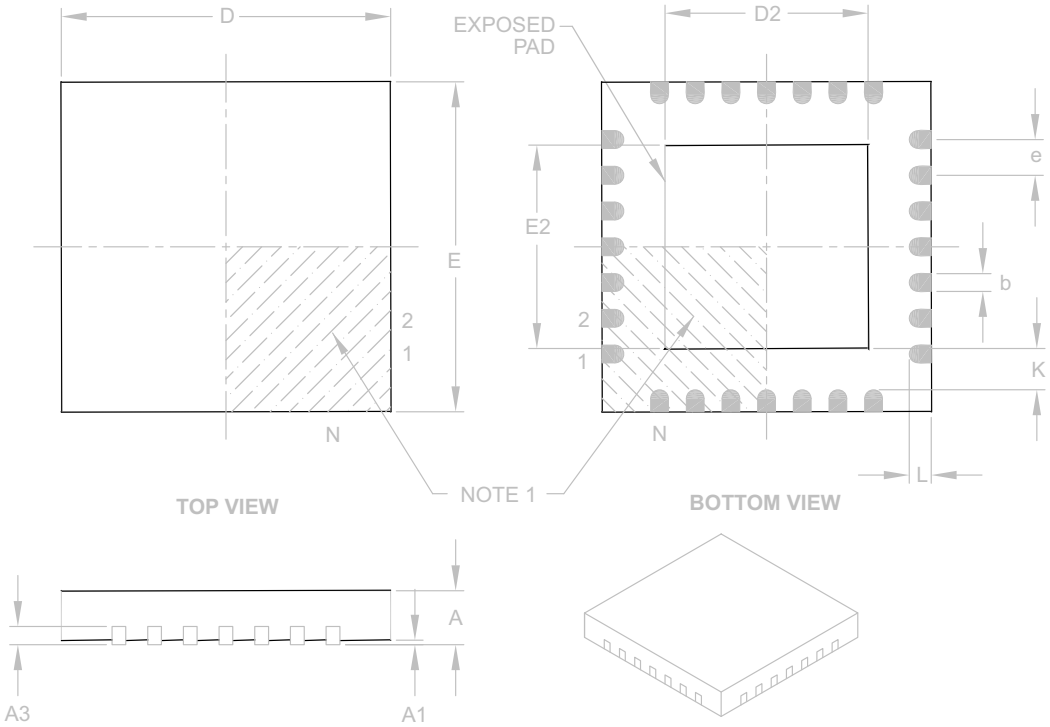


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.70
Contact Width	b	0.23	0.38	0.43
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-124B

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 11.0 "I/O Ports"	Removed Table 11-1 and added reference to pin diagrams for I/O pin availability and functionality. Added paragraph on ADPCFG register default values to **Section 11.3 "Configuring Analog Port Pins"**. Added Note box regarding PPS functionality with input mapping to **Section 11.6.2.1 "Input Mapping"**.
Section 18.0 "Serial Peripheral Interface (SPI)"	Added Note 2 and 3 to the SPIxCON1 register (see Register 18-2).
Section 20.0 "Universal Asynchronous Receiver Transmitter (UART)"	Updated the Notes in the UxMODE register (see Register 20-1). Updated the UTXINV bit settings in the UxSTA register and added Note 1 (see Register 20-2).
Section 21.0 "Enhanced CAN (ECAN™) Module"	Changed bit 11 in the ECAN Control Register 1 (CiCTRL1) to Reserved (see Register 21-1).
Section 22.0 "10-bit/12-bit Analog-to-Digital Converter (ADC1)"	Replaced the ADC1 Module Block Diagrams with new diagrams (see Figure 22-1 and Figure 22-2). Updated bit values for ADCS<7:0> and added Notes 1 and 2 to the ADC1 Control Register 3 (AD1CON3) (see Register 22-3). Added Note 2 to the ADC1 Input Scan Select Register Low (AD1CSSL) (see Register 22-7). Added Note 2 to the ADC1 Port Configuration Register Low (AD1PCFGL) (see Register 22-8).
Section 23.0 "Audio Digital-to-Analog Converter (DAC)"	Updated the midpoint voltage in the last sentence of the first paragraph. Updated the voltage swing values in the last sentence of the last paragraph in **Section 23.3 "DAC Output Format"**.
Section 24.0 "Comparator Module"	Updated the Comparator Voltage Reference Block Diagram (see Figure 24-2).
Section 25.0 "Real-Time Clock and Calendar (RTCC)"	Updated the minimum positive adjust value for CAL<7:0> in the RTCC Calibration and Configuration (RCFGCAL) Register (see Register 25-1).
Section 28.0 "Special Features"	Added Note 1 to the Device Configuration Register Map (see Table 28-1). Updated Note 1 in the dsPIC33F Configuration Bits Description (see Table 28-2).